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Kingbright WP1503GC

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### T-1 3/4(5mm) SOLID STATE LAMP

Part Number: WP1503GC

Green

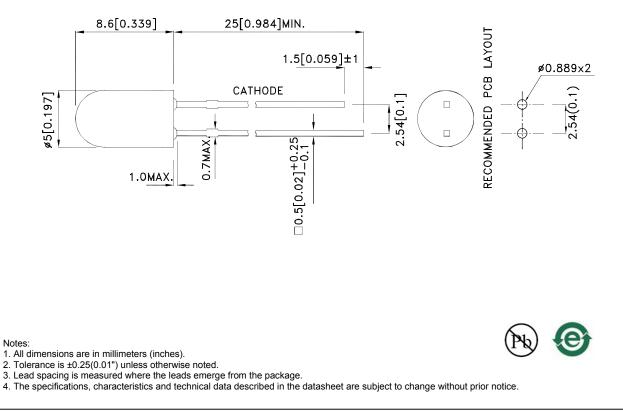
#### Features

- Low power consumption.
- Versatile mounting on P.C. board or panel.
- T-1 3/4 diameter flangeless package.
- Reliable and rugged.
- RoHS compliant.

#### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### **Package Dimensions**



SPEC NO: DSAF2379



#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP1503GC	Green (GaP)	Water Clear	50	100	30°

Notes:

1.01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2.Luminous intensity/ luminous Flux: +/-15%.

3.Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Green	2.2	2.5	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

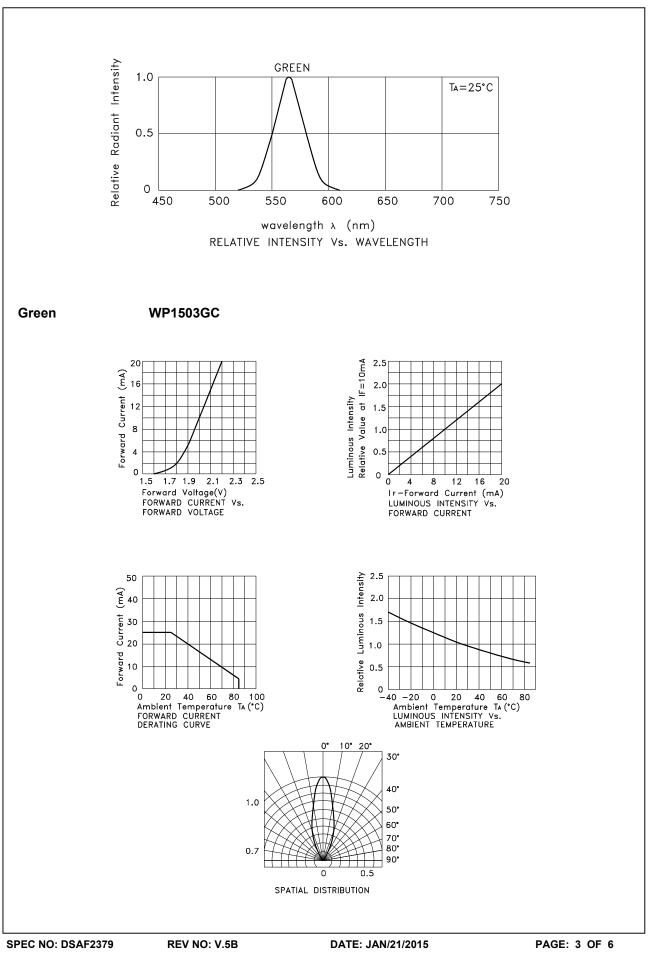
Absolute Maximum Ratings at TA=25°C

4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

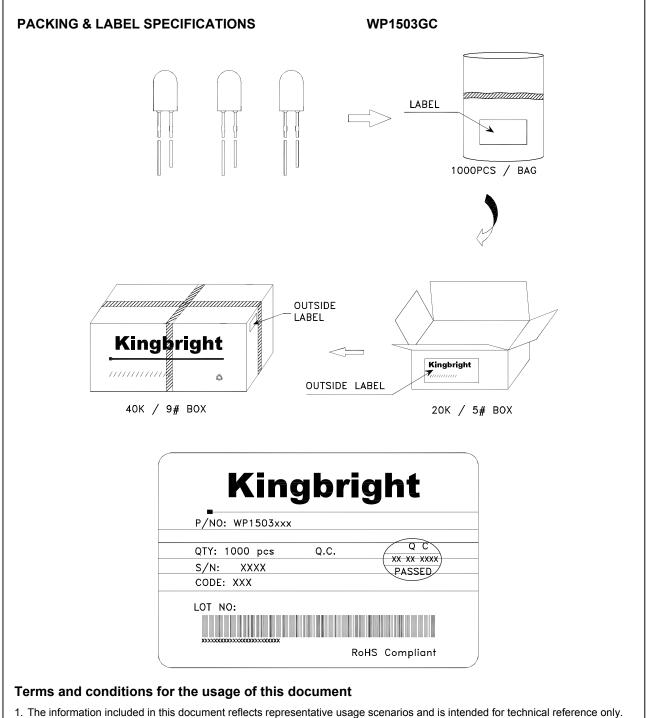
#### Parameter Green Units Power dissipation 62.5 mW DC Forward Current 25 mΑ Peak Forward Current [1] 140 mΑ **Reverse Voltage** 5 V -40°C To +85°C Operating/Storage Temperature Lead Solder Temperature [2] 260°C For 3 Seconds Lead Solder Temperature [3] 260°C For 5 Seconds Notes 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.

3. 5mm below package base.









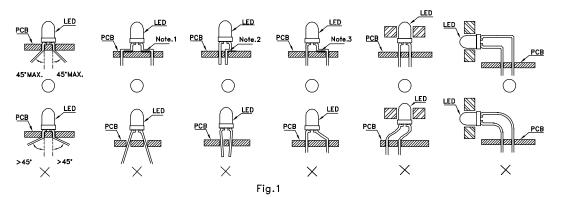
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#### PRECAUTIONS

#### 1. Storage conditions:

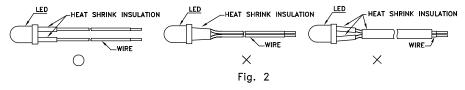
- a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- b.LEDs should be stored with temperature  $\leq$  30°C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



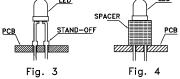
" $\bigcirc$ " Correct mounting method " $\times$ " Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)

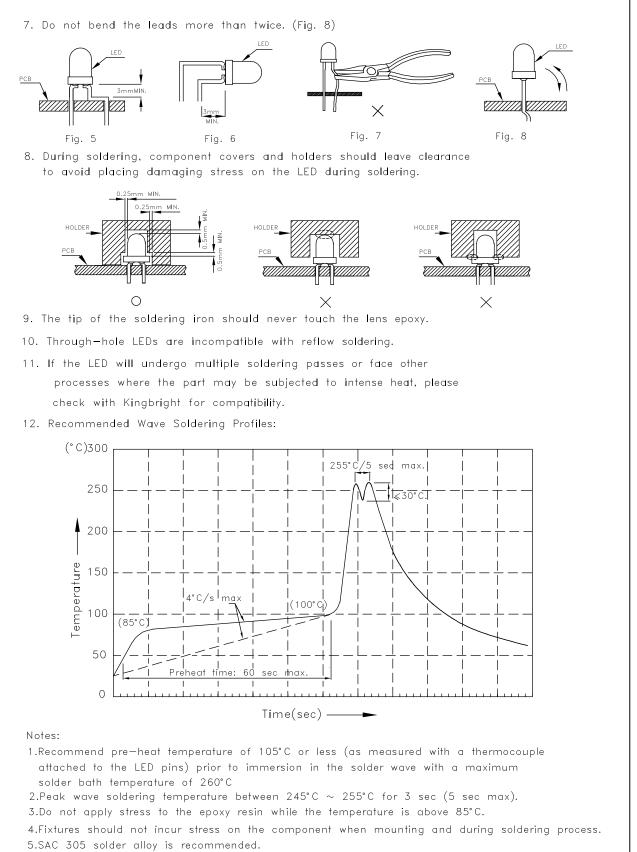


4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)





6.No more than one wave soldering pass.